

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Wei Hu</td> <td>06/03/2012</td> </tr> <tr> <td>Gang Li</td> <td>06/06/2012</td> </tr> <tr> <td>Jia-Xin Mei</td> <td>06/03/2012</td> </tr> </tbody> </table>		Name	Execution Date	Wei Hu	06/03/2012	Gang Li	06/06/2012	Jia-Xin Mei	06/03/2012				
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RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>MEMSensing Microsystems Technology Co., Ltd</td> </tr> <tr> <td>Street Address:</td> <td>Suit 213B, A2 Building, BioBay 218 Xing Hu Road</td> </tr> <tr> <td>Internal Address:</td> <td>Suzhou Industrial Park</td> </tr> <tr> <td>City:</td> <td>Suzhou City</td> </tr> <tr> <td>State/Country:</td> <td>CHINA</td> </tr> <tr> <td>Postal Code:</td> <td>215000</td> </tr> </table>		Name:	MEMSensing Microsystems Technology Co., Ltd	Street Address:	Suit 213B, A2 Building, BioBay 218 Xing Hu Road	Internal Address:	Suzhou Industrial Park	City:	Suzhou City	State/Country:	CHINA	Postal Code:	215000
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PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13561194</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13561194								
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Application Number:	13561194												
CORRESPONDENCE DATA													
<p>Fax Number: 3239340202          Phone: 323-934-2300          Email: LA_Mail@la.ladas.com</p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: LADAS &amp; PARRY          Address Line 1: 5670 WILSHIRE BOULEVARD, SUITE 2100          Address Line 4: LOS ANGELES, CALIFORNIA 90036-5679</p>													
ATTORNEY DOCKET NUMBER:	B-7462 627506-9												
NAME OF SUBMITTER:	Joseph M. Kobzeff												
<p>Total Attachments: 4          source=627506_assignment#page1.tif          source=627506_assignment#page2.tif          source=627506_assignment#page3.tif          source=627506_assignment#page4.tif</p>													

OP \$40.00 13561194

Attorney's Docket No.

B-7462 627506-9

Patent

For: ☒ U.S. and/or ☐ Foreign Rights  
For: ☒ U.S. Application or ☐ U.S. Patent  
For: ☐ PCT Application  
By: ☒ Inventor(s) or ☐ Present Owner

### ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNORS:  
(inventor(s) or person(s) or  
entity(ies) who own the invention)

(1) Wei Hu  
(type or print name(s) of ASSIGNOR(S))

Suit 213B, A2 Building, BioBay  
218 Xing Hu Road, Suzhou Industrial Park  
China 215000

\_\_\_\_\_  
(Address)

CN  
(Nationality)

(2) Gang Li  
(type or print name(s) of ASSIGNOR(S))

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218 Xing Hu Road, Suzhou Industrial Park  
China 215000

\_\_\_\_\_  
(Address)

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(Nationality)

(3) Jia-Xin Mei  
(type or print name(s) of ASSIGNOR(S))

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218 Xing Hu Road, Suzhou Industrial Park  
China 215000

\_\_\_\_\_  
(Address)

CN  
(Nationality)

(Assignment of Invention [16-3]--page 1 of 3)

hereby confirm that ASSIGNORS sell, assign and transfer to

**ASSIGNEE:**

MEMSensing Microsystems Technology Co., Ltd

(type or print name(s) of ASSIGNEE(S))

Suit 213B, A2 Building, BioBay

218 Xing Hu Road, Suzhou Industrial Park

China 215000

(Address)

CN

(Nationality)

and the successors, assigns and legal representatives of the ASSIGNEE  
(complete one of the following)

☒ the entire right, title and interest

☐ an undivided \_\_\_\_\_ percent ( \_\_\_\_\_ % ) interest for the

United States and its territorial possessions

(check the following box if foreign rights are also to be assigned)

☐ and in all foreign countries, including all rights to claim

priority, in and to any and all improvements which are disclosed in the invention  
entitled :

CHIP WITH INTEGRATED CIRCUIT AND MICRO-SILICON CONDENSER  
MICROPHONE INTEGRATED ON SINGLE SUBSTRATE AND METHOD FOR  
MAKING THE SAME

(check and complete (a), (b), (c) or (d)) and which is found in

(a) ☐ U.S. patent application executed on even date herewith

(b) ☐ U.S. patent application executed on \_\_\_\_\_

☒ To comply with 37 CFR 3.21 for recordal of this assignment, I, an  
ASSIGNOR signing below, hereby authorize and request my attorney, as named  
in the Declaration and Power of Attorney I executed for this invention on the  
execution date stated above, to insert below the filing date and application  
number when it becomes known.

(c) ☐ U.S. Application serial no. \_\_\_\_\_ filed on \_\_\_\_\_

(d) ☐ International application no. \_\_\_\_\_

(e) ☐ U.S. Patent no. \_\_\_\_\_ issued \_\_\_\_\_

(Assignment of Invention [16-3]--page 2 of 3)

☐ A change of address to which correspondence is to be sent regarding patent maintenance fees is being sent separately.

(also check (F) if foreign application(s) is also being assigned)

(f) ☐ and any legal equivalent thereof in a foreign country, including the right to claim priority and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNORS hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNORS further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNORS and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/We have hereunto set hand and seal this  
3 day of June, 2012 (date of signing).

Wei Hu  
Name of Assignor(s)

Wei Hu  
Signature of ASSIGNOR(S)

IN WITNESS WHEREOF, I/We have hereunto set hand and seal this  
6 day of June, 2012 (date of signing).

Gang Li  
Name of Assignor(s)

Gang Li  
Signature of ASSIGNOR(S)

IN WITNESS WHEREOF, I/We have hereunto set hand and seal this  
3 day of June, 2012 (date of signing).

Jia-Xin Mei  
Name of Assignor(s)

(Assignment of Invention [16-3]--page 3 of 3)

Jia-Xin Mei  
Signature of ASSIGNOR(S)

(Assignment of Invention [16-3]--page 4 of 3)